



CBR-SMD RF COG, Ceramic, 0.9 pF, +/-0.1 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	0.3 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
Т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

VV	0.311111 +/ -0.0311111	voitage DC	30 VDC
Т	0.3mm +/-0.03mm	Dielectric Withstanding Voltage	125 VDC
В	0.15mm +/-0.05mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.239%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade H
Packaging Quantity	15000	Insulation Resistance	10 GOhms

Specifications	
Capacitance	0.9 pF
Tolerance	+/-0.1 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.239%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	418

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